

App. No. 10/826,508
Office Action Dated July 8, 2005

Amendments to the Claims:

This listing of claims will replace all prior versions and listing of claims in the application.

Claims 1, 5, 7, 9, and 11 are amended.

Claims 4, 6, 8, and 10 are canceled.

Listing of Claims:

1. (Currently Amended) A bonding structure for bonding resin comprising a bonding layer formed on a copper surface, the bonding layer comprising an alloy of:
 - (a) copper;
 - (b) tin; and
 - (c) ~~at least~~ one metal (third metal) selected from the group consisting of: silver, zinc, aluminum, ~~titanium~~, bismuth, ~~chromium~~, ~~iron~~, cobalt, and nickel, ~~palladium~~, ~~gold~~, and ~~platinum~~;wherein the copper is contained in an amount of ~~[[1 to 50]]~~ 5 to 45 atom %, the tin is contained in an amount of ~~20 to 98~~ 30 to 90 atom %, and the third metal is contained in an amount of ~~[[1 to 50]]~~ 2 to 45 atom %, and
the bonding layer has a thickness of not less than 0.001 μm and not more than ~~[[1]]~~ 0.5 μm , and
wherein the bonding layer is useful for an adhesive layer to resin.
2. (Original) The bonding layer according to claim 1,
wherein the copper surface is smooth.
3. (Original) The bonding layer according to claim 1,
wherein the copper surface is rough.

App. No. 10/826,508
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4. (Canceled)
5. (Currently Amended) The bonding layer according to claim [[4]]1,
wherein the bonding layer contains the copper in an amount in a range of 10 to 40 atom %.
6. (Canceled)
7. (Currently Amended) The bonding layer according to claim [[6]]1,
wherein the bonding layer contains the tin in an amount in a range of 40 to 80 atom %.
8. (Canceled)
9. (Currently Amended) The bonding layer according to claim [[8]]1,
wherein the bonding layer contains the third metal in an amount in a range of 3 to 40 atom %.
10. (Canceled)
11. (Currently Amended) The bonding layer according to claim [[10]] 1,
wherein the bonding layer has a thickness in a range of 0.001 to 0.1 μm .